

ABSTRACT OF THE DISCLOSURE

A bonding apparatus configured to bond dies to a substrate, wherein the substrate includes first devices on a surface for bonding to the dies, the die includes a second device that is to be electrically connected to the first device, the bonding apparatus includes a carrier holder to hold horizontally a carrier on which the dies are mounted, a substrate holder to hold horizontally the substrate, a substrate moving unit to move the substrate together with the substrate holder, a first conveyor to receive the die from the carrier and convey the die, and a mounting unit to receive the die from the first conveyor and mount the received die onto the substrate, the carrier holder and the substrate holder are disposed apart from each other in a vertical direction, and when viewed from above, a center of the carrier is located within a movement range of the substrate.

FIG.6